

(0.80 mm) .0315"

# **HIGH-SPEED GROUND PLANE HEADER**

Integral metal plane

#### **SPECIFICATIONS**

For complete specifications and recommended PCB layouts see www.samtec.com?QTE

Insulator Material: Liquid Crystal Polymer Terminal Material: Phosphor Bronze Plating: Au or Sn over 50 µ" (1.27 µm) Ni

**Current Rating:** Contact: 2 A per pin

(2 pins powered) Ground Plane: 23 A per ground plane (1 ground plane powered)

Operating Temp Range:
-55 °C to +125 °C

Voltage Rating: 225 VAC mated with QSE & 5 mm Stack Height Max Cycles: 100

**RoHS Compliant:** 

### **Board Mates:**

#### Cable Mates:

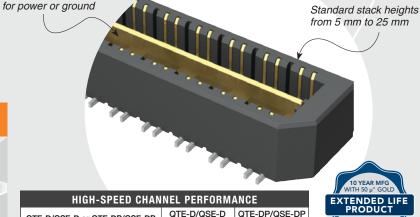
EQCD, EQDF (See Also Available Note)

#### Standoffs:

#### **POWER/SIGNAL APPLICATION**



UMPT/UMPS for flexible two-piece power/signal solutions



QTE-D/QSE-D or QTE-DP/QSE-DP @ 5 mm Mated Stack Height

Rating based on Samtec reference channel.For full SI performance data visit Samtec.comor contact SIG@samtec.com

**PLATING** 

**OPTION** 

= Gold Flash on

Signal Pins and

Ground Plane,

Matte Tin on tails

**OTHER OPTION** 

# **PROCESSING**

Lead-Free Solderable: Yes SMT Lead Coplanarity: (0.10 mm) .004" max (020-060)

Board Stacking: For applications requiring more than two connectors per board contact ipg@samtec.com

## **RECOGNITIONS**

For complete scope of recognitions see www.samtec.com/quality



### ALSO AVAILABLE (MOQ Required)

- 15 mm, 22 mm and 30 mm stack height
- 30 μ" (0.76 μm) Gold (Specify -H plating for Data Rate cable mating applications.)
- Edge Mount, Guide Posts, Screw Down & Friction Lock
- 56 (-DP), 80, 100 positions per row
- Retention Option

Some lengths, styles and options are non-standard, non-returnable.

# **PINS PER ROW** NO. OF PAIRS

-020, -040, -060 (40 total pins per bank = -D)

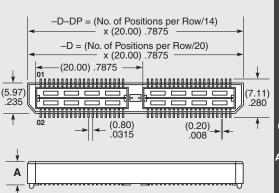
-014, -028, -042 (14 pairs per bank = -D-DP)

Specify LEAD STYLE

**LEAD** 

STYLE

from chart







= 10 µ" (0.25 µm) Gold on Signal Pins and Ground Plane, Matte Tin on tails

= Electro-Polished

Selective 50 μ" (1.27 μm) min Au over 150μ" (3.81 μm) Ni on Signal Pins in contact area, 10 μ" (0.25 μm) min Au over 50 μ" (1.27 μm) Ni on Ground Plane in contact area, Matte Tin over 50µ" (1.27 µm) min Ni on all solder tails

C Plating passes
 year MFG testing

–D = Single-Ended -D-DP Differential Pair

(-01 only)

= (7.00 mm) .275" DIA Polyimide Film Pick & Place Pad

-TR Tape & Reel Packaging (N/A -05 & -07 lead style)

\_1 = Latching Option (N/A on -042 & 060 positions)

QTE LEAD STYLE	А	HEIGHT WITH QSE*
-01	(4.27) .168	(5.00) .197
-02	(7.26) .286	(8.00) .315
-03	(10.27) .404	(11.00) .433
-04	(15.25) .600	(16.00) .630
-05	(18.26) .718	(19.00) .748
-07	(24.24) .954	(25.00) .984
-09	(13.26) .522	(14.00) .551

\*Processing conditions will affect mated height. See SO Series for board space tolerances

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